



Material Content Data Sheet



Sales Product Name				IPS50R520CP		Issued		1. August 2018	
MA#				MA000907878					
Package				PG-TO251-3-311		Weight*		333.00 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.934	1.18	1.18	11815	11815	
leadframe	non noble metal	iron	7439-89-6	0.156	0.05		467		
	inorganic material	phosphorus	7723-14-0	0.047	0.01		140		
	non noble metal	copper	7440-50-8	155.372	46.64	46.70	466581	467188	
wire	non noble metal	aluminium	7429-90-5	5.398	1.62	1.62	16210	16210	
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.953	0.59		5866		
	plastics	brominated resin	-	2.093	0.63		6285		
	organic material	carbon black	1333-86-4	2.232	0.67		6704		
	plastics	epoxy resin	-	18.835	5.66		56561		
	inorganic material	silicondioxide	60676-86-0	114.405	34.36	41.91	343557	418973	
leadfinish	non noble metal	tin	7440-31-5	3.002	0.90	0.90	9014	9014	
plating	inorganic material	phosphorus	7723-14-0	0.004	0.00		11		
	non noble metal	nickel	7440-02-0	1.555	0.47	0.47	4668	4679	
solder	noble metal	silver	7440-22-4	0.084	0.03		253		
	non noble metal	tin	7440-31-5	0.067	0.02		203		
	non noble metal	lead	7439-92-1	3.220	0.97	1.02	9671	10127	
heatspreader	non noble metal	iron	7439-89-6	0.021	0.01		62		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		19		
	non noble metal	copper	7440-50-8	20.617	6.19	6.20	61913	61994	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com